L'Number	Hits	Search Text	DB	Time stamp
1	909531	(upper or top\$5 or high\$3) with layer\$5	USPAT;	2004/07/30
			US-PGPUB;	09:14
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	143656	((ic\$1 or integrated adj2 circuit\$2 or chip\$5) with	USPAT;	2004/07/30
		layer\$1)	US-PGPUB;	09:15
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
3	15969	((upper or top\$5 or high\$3) with layer\$5) with	USPAT;	2004/07/30
		(config\$10 or custom\$10)	US-PGPUB;	09:48
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
4	631	(((ic\$1 or integrated adj2 circuit\$2 or chip\$5) with	USPAT;	2004/07/30
	<del>-</del>	layer\$1)) same (((upper or top\$5 or high\$3) with	US-PGPUB;	09:16
		layer\$5) with (config\$10 or custom\$10))	EPO; JPO;	
		, , , , , , , , , , , , , , , , , , , ,	DERWENT;	
			IBM_TDB	
5	345	(((upper or top\$5 or high\$3) with layer\$5) with	USPAT;	2004/07/30
-	0.5	(config\$10 or custom\$10)) with (short\$5 or fus\$5)	US-PGPUB;	09:18
		(22	EPO, JPO;	
		· .	DERWENT;	
			IBM_TDB	
.6	21	(((ic\$1 or integrated adj2 circuit\$2 or chip\$5) with	USPAT;	2004/07/30
	61	layer\$1)) same ((((upper or top\$5 or high\$3) with	US-PGPUB;	09:26
		layer\$5) with (config\$10 or custom\$10)) with	EPO; JPO;	09.20
		(short\$5 or fus\$5))	DERWENT;	
		(SUOLIAS OLIDAS))	IBM_TDB	
7	20745	maggiute ad if levent?	_	2004/07/20
7	30745	passiv\$8 adj5 layer\$3	USPAT;	2004/07/30
			US-PGPUB;	09:28
			EPO; JPO;	
			DERWENT;	
_	5070	///: #4	IBM_TDB	2004/07/20
8	5079	(((ic\$1 or integrated adj2 circuit\$2 or chip\$5) with	USPAT;	2004/07/30
		layer\$1)) same (passiv\$8 adj5 layer\$3)	US-PGPUB;	09:28
			EPO; JPO;	
		·	DERWENT;	
_		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	IBM_TDB	å00440 <del>7</del> := =
9	214	(((((ic\$1 or integrated adj2 circuit\$2 or chip\$5) with	USPAT;	2004/07/30
		layer\$1)) same (passiv\$8 adj5 layer\$3)) same	US-PGPUB;	09:29
		(config\$10 or custom\$10)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
10	72	(((((ic\$1 or integrated adj2 circuit\$2 or chip\$5) with	USPAT;	2004/07/30
		layer\$1)) same (passiv\$8 adj5 layer\$3)) same	US-PGPUB;	09:29
		(config\$10 or custom\$10)) same ((upper or top\$5 or	EPO; JPO;	
		high\$3) with layer\$5)	DERWENT;	
			IBM_TDB	

11	1154	((upper or top\$5 or high\$3) with layer\$5) with	USPAT;	2004/07/30
11	1154	custom\$10	US-PGPUB;	09:49
		Custompto	EPO; JPO;	05.45
			DERWENT;	•
			IBM_TDB	
12	83	(((upper or top\$5 or high\$3) with layer\$5) with	USPAT;	2004/07/30
		custom\$10) same (((ic\$1 or integrated adj2 circuit\$2	US-PGPUB;	09:49
		or chip\$5) with layer\$1))	EPO; JPO;	
		, , , , , , , , , , , , , , , , , , , ,	DERWENT;	
			IBM_TDB	
-	2	6718424.pn.	USPAT;	2004/07/29
			US-PGPUB;	10:45
			EPO; JPO;	
		·	DERWENT;	
			IBM_TDB	
-	2	6151651.pn.	USPAT;	2004/07/29
			U5-PGPUB;	13:33
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
- '	91925	(ic\$1 or integrated adj2 circuit\$2) with layer\$1	USPAT;	2004/07/29
			US-PGPUB;	13:34
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	143656	(ic\$1 or integrated adj2 circuit\$2 or chip\$5) with	USPAT;	2004/07/29
		layer\$1	US-PGPUB;	13:37
			EPO; JPO;	
			DERWENT;	
-	10015	-1 160 11 (/	IBM_TDB	2004/07/00
_	19915	short\$3 with ((upper or top\$5 or high\$3) with	USPAT;	2004/07/29
		layer\$1)	US-PGPUB; EPO; JPO;	13:37
			DERWENT;	
			IBM_TDB	
_	768	((ic\$1 or integrated adj2 circuit\$2 or chip\$5) with	USPAT;	2004/07/30
	,00	layer\$1) same (short\$3 with ((upper or top\$5 or	US-PGPUB;	09:15
		high\$3) with layer\$1))	EPO; JPO;	
		· · · · · · · · · · · · · · · · · · ·	DERWENT;	
			IBM_TDB	
-	86	(short\$3 with ((upper or top\$5 or high\$3) with	USPAT;	2004/07/29
		layer\$1)) with delay\$5	US-PGPUB;	13:38
			EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
-	32	((ic\$1 or integrated adj2 circuit\$2 or chip\$5) with	USPAT;	2004/07/29
		layer\$1) same ((short\$3 with ((upper or top\$5 or	US-PGPUB;	13:37
		high\$3) with layer\$1)) with delay\$5)	EPO; JPO;	
			DERWENT;	
			IBW_TDB	

			T	
-	18	((ic\$1 or integrated adj2 circuit\$2 or chip\$5) with	USPAT;	2004/07/29
·		layer\$1) same ((short\$3 with ((upper or top\$5 or	US-PGPUB;	13:37
		high\$3) with layer\$1)) with delay\$5)	EPO; JPO;	
		,	DERWENT;	
		·	IBW_TDB	
-	145730	(ic\$1 or integrated adj2 circuit\$2 or chip\$5) with layer\$5	USPAT;	2004/07/29
			US-PGPUB;	13:37
		. '	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	20128	short\$3 with ((upper or top\$5 or high\$3) with	USPAT;	2004/07/29
		layer\$5)	US-PGPUB;	13:38
			EPO; JPO;	
	-		DERWENT;	
			IBM_TDB	
-	87	(short\$3 with ((upper or top\$5 or high\$3) with	USPAT;	2004/07/29
		layer\$5)) with delay\$5	U5-PGPUB;	13:38
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	18	((ic\$1 or integrated adj2 circuit\$2 or chip\$5) with	USPAT;	2004/07/29
		layer\$5) same ((short\$3 with ((upper or top\$5 or	US-PGPUB;	13:40
		high\$3) with layer\$5)) with delay\$5)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	779	((ic\$1 or integrated adj2 circuit\$2 or chip\$5) with	USPAT;	2004/07/30
		layer\$5) same (short\$3 with ((upper or top\$5 or	US-PGPUB;	09:13
		high\$3) with layer\$5))	EPO; JPO;	
			DERWENT;	
		•	IBM_TDB	